Spectroscopic Ellipsometry Study on Defects Generation in GeO₂/Ge stacks

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1. Introduction

It is required to control the properties of Ge/dielectric interfaces precisely to realize high-performance Ge MISFETs, however, the thermodynamically unstable nature of Ge native oxides [1, 2] has been a big issue to overcome. It is reported that the GeO volatilization is caused by the GeO₂/Ge interface reaction, and that volatilization is the origin of the deterioration of GeO₂/Ge MIS characteristics [2]. We have already reported that spectroscopic ellipsometry (SE) measurement is a powerful method to clarify the defects in GeO₂/Ge stacks [3]. In this study, the defect states generation in GeO₂ films was further investigated by using SE measurements.

2. Experimental

The GeO₂ films were deposited by rf-sputtering of GeO₂ target on HF-treated Ge (100) wafers, followed by the annealing in N₂ or O₂ ambient at 500 - 700°C. The refractive indices (*n*) and extinction coefficients (*k*) of GeO₂ films were evaluated with SE, by assuming the model with a single layer on the substrate. The "point-by-point" calculation at each wavelength [3] was employed, without assuming any dielectric functions for GeO₂.

3. Results and Discussions

The spectra of *n* of sputtered GeO₂ films do not change significantly, however, those of *k* change dramatically by N₂ annealing [3]. The spectra of *k* are shown as a function of photon energy in **Fig. 1**, for the films annealed in N₂ at 600°C for various annealing time. The as-sputtered film shows a sharp increase of *k* at ~ 6 eV, which corresponds to the bandgap of GeO₂, however, a gradual increase of *k* in the region of 5 - 6 eV emerges after annealing. This sub-gap photo-absorption will be attributed to a generation of significant density of defect states. The emergence of the two peaks at ~5.1 eV and ~5.8 eV in the spectra suggest the generation of two kinds of defect states simultaneously in the deteriorated GeO₂ films.

Next, k spectra of bi-layered GeO₂ films, consisting of annealed and non-annealed (fresh) layers, were investigated in order to distinguish whether those sub-gap defects are bulk defects in GeO₂ or interface defects at GeO₂/Ge. The 1st deteriorated layers with different thicknesses were prepared by N₂ annealing at 600°C, followed by the deposition of the 2nd fresh layers to attain a common total thickness, as depicted in **Fig. 2**. The k values at 5.1 eV and 5.8 eV of those four samples are plotted in **Fig. 3**, which clearly shows that the amount of sub-gap defects is proportional to the thickness ratio of annealed layer to the total layer. Thus the observed defects by SE measurements are not the defects formed at GeO₂/Ge interface, but the bulk defects uniformly existing in the annealed film.

Next, the relationship between the sub-gap defects generation with GeO volatilization was investigated. In **Fig. 4** (a) and (b), the k values at 5.1 eV and 5.8 eV of the films



Fig.1 Extinction coefficient (*k*) of GeO₂ films annealed at 600° C for various time evaluated by spectroscopic ellipsometry. Sub-gap photo-absorption increases in the energy region below the bandgap energy (~6.1eV) by annealing. The emergence of two peaks at ~5.1eV and ~5.8eV correspond to the generation of two kinds of defect states in GeO₂ films.



Fig.2 Schematic of samples (A)-(D) with GeO₂ bi-layers. The 1st layers (annealed) with different thicknesses (95, 65, and 35 nm) were prepared by annealing sputtered films at 600°C in N₂, followed by the deposition of the 2nd layers (fresh). The thicknesses of the 2nd layers were controlled to obtain a common total thickness (120~125 nm). The ratios of the annealed layer thickness to the total (annealed + fresh) thickness are: (A) 0.76, (B) 0.52, (C) 0.29, and (D) 0, respectively. The sample (D) consists only of 2nd (fresh) layer.



Fig.3 Extinction coefficient (*k*) values at 5.1 eV and 5.8 eV for the GeO₂ bi-layers (A) ~ (D) depicted in Fig.2, as a function of the ratio of the annealed layer thickness to the total thickness. By increasing the annealed/total thickness ratio, the intensity of sub-gap absorption increases, which clearly indicates that the sub-gap states are attributable to the bulk defects in deteriorated GeO₂ layers, rather than the interface defects at GeO₂/Ge.



Fig. 4 Relationship between the change of the film thickness by GeO volatilization and the sub-gap defects generation, which is corresponding to the increase of the extinction coefficients (k) at (a) 5.1 eV and (b) 5.8 eV. The amount of GeO volatilization determines the generated defect density, irrespective of annealing temperature and time.

annealed at 500°C - 700°C for various time, are plotted as a function of thickness change (ΔT_{ox}) by annealing. It should be noted that the sub-gap defect density seems to be described as a function of the amount of GeO volatilized from the film, irrespective of the annealing temperature, or annealing time. In addition, the fact that the *k* spectrum of the GeO₂ film deposited on surface-oxidized Si (100) wafer does not show any sub-gap photo-absorption even after annealing at 650°C [3] also supports our consideration, because it is reported the GeO volatilization does not occur from the GeO₂ films deposited on surface-oxidized Si substrate in this temperature range [2].

It has been reported that oxygen deficient GeO₂ bulk glass shows a UV-absorption band at ~ 5 eV [4]. From theoretical and experimental studies, this absorption band is considered to be attributable to Ge²⁺ defects or oxygen vacancies [4,5]. It should be noted that the energy regions of these defects are quite coincident with what we have observed as the sub-gap defect states for the deteriorated films. Thus it is reasonable to consider that GeO₂ films have a tendency to become oxygen deficient in N₂ ambient, and that deficiency increases through the generation and volatilization of GeO. Thus the amount of volatilized GeO determines the amount of sub-gap defects in GeO₂ films.

From thermodynamic considerations, it is reasonable to



Fig. 5 Values of extinction coefficients (*k*) at 5.1 eV and 5.8 eV as a function oxygen pressure (pO₂) in the annealing ambient for the films annealed at 550°C (initial thickness: 140 nm). The sub-gap defect generation was clearly detected after lower- pO_2 annealing but completely suppressed after higher- pO_2 (>30atm) annealing.

consider that the annealing in O2 ambient with high pressure reduces the oxygen deficiency in GeO₂. Thus the effects of O_2 pressure (pO_2) in the annealing ambient on k spectra of GeO₂ films were investigated. As shown in Fig. 5, the sub-gap photo-absorption dramatically decreases as pO_2 in the annealing ambient increases. This result shows that the density of sub-gap defects strongly correlates with the oxygen deficiency of the film. It is found that the sub-gap defects are generated even by the annealing in oxygen ambient, as long as pO_2 is below ~ 30 atm (at 550°C). The oxygen deficiency in GeO_2 is determined by the temperature and pO_2 , as schematically drawn in Fig. 6, which explains why high pO_2 is required to grow a high-quality thermal GeO₂ film at higher temperature [6], whereas 1 atm-O₂ is enough to form a relatively good quality film at lower temperatures. In general, the annealing at higher temperature is beneficial to improve the film quality, thus the control of pO_2 at high temperature is inevitably important.

4. Conclusions

The deterioration of GeO₂/Ge stack, through a generation of bulk defects in GeO₂ film, was clearly observed as an increase of sub-gap photo-absorption of the film. It was found that the amount of GeO volatilized from the stack determined the density of the sub-gap defect states. The generation of those defects was suppressed when the film was annealed in high pO_2 ambient since those defects correlate with oxygen deficiency of the films.

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Fig. 6 Schematic of defect density in GeO₂ films annealed in different ambient (N₂, 1-atm O₂, and high-pressure O₂) at various temperatures. At higher temperature, a higher- pO_2 is required to improve the film quality by suppressing the oxygen deficiency, while a lower pO_2 is enough to suppress it at lower temperature. The dotted line represents the improvement of the film quality by a structural relaxation when GeO volatilization is completely suppressed.